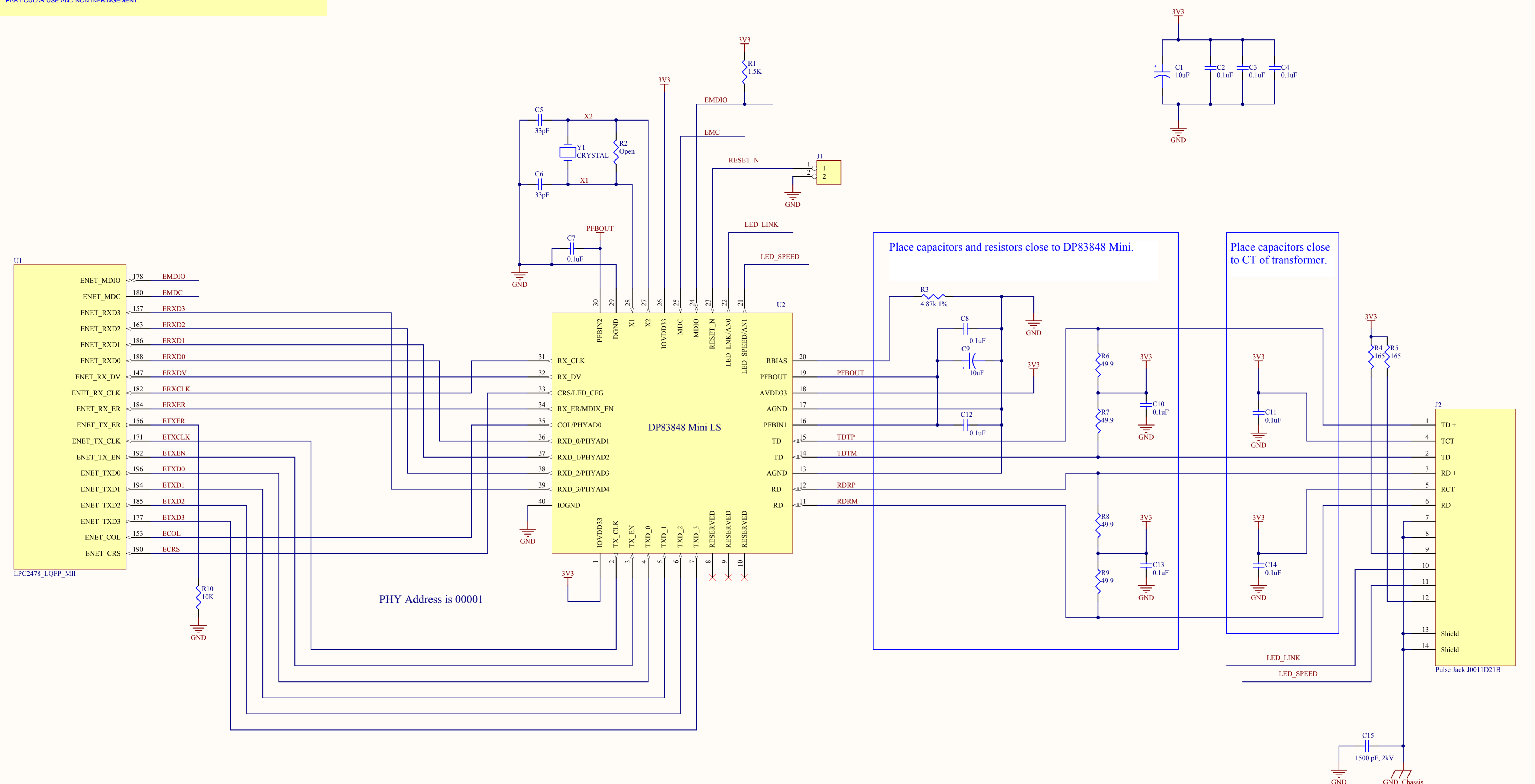


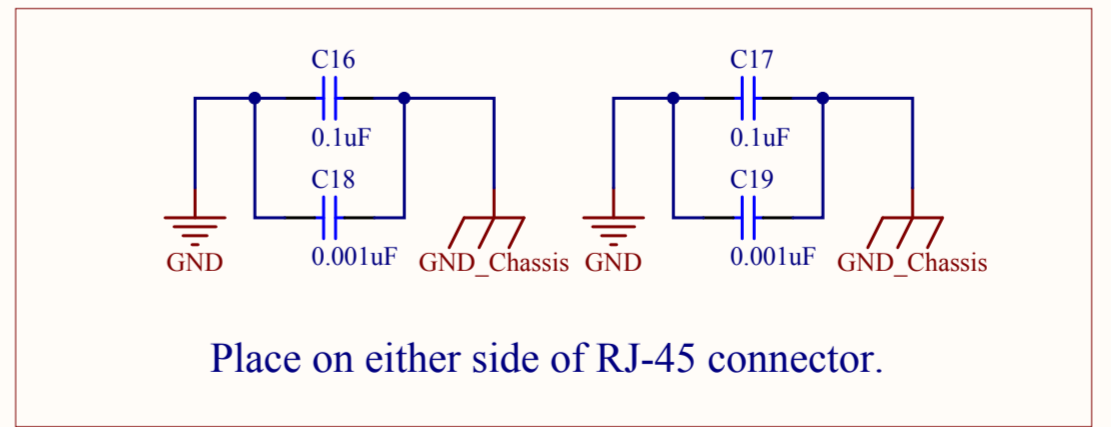
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Note: For Reference Only

DP83848Mini LS with NXP LPC2478_LQFP



Note: The packaging DAP should be soldered to a thermal relief plane, typically GND.



File	NSC DP83848Mini LS / NXP LPC2478 App. Note		
Size	Document Number	Rev	
.C	ASPG - Interface Division - Working Draft: CPU & PHY MII Connections	A	
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